Special Issue

Printed and Flexible Electronics: Devices, Materials, and Integration

Message from the Guest Editors

Recent progress in flexible and printed electronics continues to reveal their vast potential. Advances in materials, deposition techniques, and design strategies are enabling printed electronics to perform excellently in a wide field of applications. It is now tangible to develop fully printed transistor arrays, artificial synapses for neuromorphic computing, biocompatible sensor systems, and many more interesting devices. Printing technologies support high-speed, large-scale manufacturing in a very cost-effective manner. Meanwhile, the combination of emerging materials such as conductive polymers, MXenes, graphene, hexagonal boron nitride, and more, allows for next-generation applications such as neuromorphic computing, in-body sensors, disposable devices and so on. Key-enabling factors for these demanding applications are the strategies for device-level integration, such as the combination of innovative materials, the passivation and interconnection with the outside world and the electrical connectivity with other electronic systems.

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Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guestedited by leading experts in selected topics of interest.

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